STK682-010-E



Thick Film Hybrid IC

2-phase Stepping Motor Driver Application Note

Overview

The STK682-010-E is a hybrid IC for use as a Bipolar, 2-phase stepping motor driver with PWM current control.

Function

- •Output on-resistance (High side 0.3 Ω , Low side 0.25 Ω , Total 0.55 Ω ; Ta = 25°C, IO = 2.5A)
- •VMmax=36V(DC), lopmax=3.0A
- •2, 1-2, W1-2, 2W1-2, 4W1-2, 8W1-2, 16W1-2, 32W1-2 phase excitation are selectable
- •With built-in automatic half current maintenance energizing function
- •Over current protection circuit
- •Thermal shutdown circuit
- •Input pull down resistance
- With reset pin and enable pin●

Specifications

bsolute Maximum Ratings at Ta = 25°C

Parameter	Symbol	Conditions	Ratings	Unit
Supply voltage	VMmax		36.0	V
Peak output current	lopmax		3.0	А
Logic input voltage	VINmax		6.0	V
VREF input voltage	VREFmax		6.0	V
Operating substrate temperature	Тс		−20 to +105	°C
Storage temperature	Tstg		-40 to +125	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Recommended Operating Conditions at $Ta = 25^{\circ}C$

Parameter	Symbol	Conditions	Ratings	Unit
Supply voltage range	VM		9.0 to 32.0	V
Logic input voltage range	VIN		0 to 5.0	V
V _{CC} input voltage range	VCC		0 to 5.0	V
VREF input voltage range	VREF		0 to 3.0	V
Output current1	lo1	1-2 Phase-ex, Tc ≤ 90°C	3.0	Α
Output current2	lo2	1-2 Phase-ex, Tc=105°C	2.5	Α
Output current3	lo3	2 Phase-ex, Tc=105°C	1.8	Α

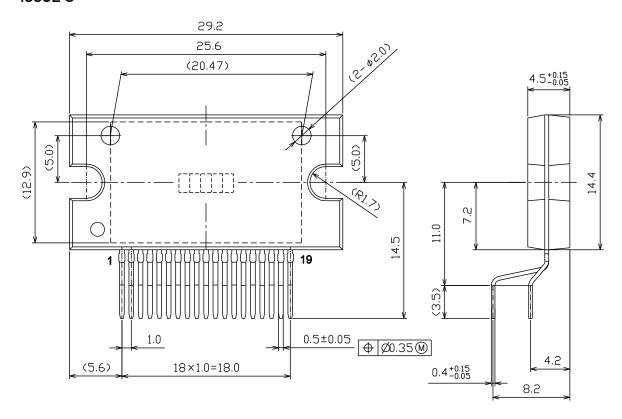
Electrical Characteristics at Ta = 25°C, $V_{CC} = 5V$

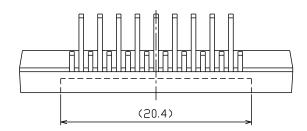
Parameter	Symbol	Conditions		Ratings		Unit
1 didilicioi	Cynnoon		min	typ	max	
Standby mode current drain	IMstn	VCC="L"		70	100	μΑ
Current drain	IM	VCC="H", ENABLE="H" No Load		3.3	4.6	mA
Thermal shutdown temperature	TSD	Design guarantee	150	180	210	°C
Thermal hysteresis width	ΔTSD	Design guarantee		40		°C
	linL1	VIN=0.8V	3	8	15	μΑ
Logic pin input current	linH1	VIN=5V	30	50	70	μΑ
V _{CC} pin input current	VCC	15pin=5V	51	83	115	μΑ
Logic input high-level voltage	Vinh	Pins 2,3,16,17,18,19	2.0			V
Logic input low-level voltage	Vinl	Pins 2,3,16,17,18,19			0.8	V
FDT pin high-level voltage	Vfdth	Pin 6	3.5			V
FDT pin middle-level voltage	Vfdtm	Pin 6	1.1		3.1	V
FDT pin low-level voltage	Vfdtl	Pin 6			0.8	V
Chopping frequency	Fch	C1=100pF	58	83	108	kHz
Chopping frequency	losc1			10		μΑ
Chopping oscillator circuit	Vtup1			1		V
threshold voltage	Vtdown1			0.5		V
VREF pin input voltage	Iref	VREF=1.5V, CLK=10kHz	-0.5			μΑ
DOWN output residual voltage	VolDO	Idown=1mA, CLK=Low		40		mV
Hold current switching frequency	Falert			1.6		Hz
Blanking time	Tb1			1		μs
Output block						
	Ronu	I _O =2.0A, high-side ON resistance		0.30	0.42	Ω
Output on-resistance	Rond	I _O =2.0A, low-side ON resistance		0.25	0.35	Ω
Output leakage current	loleak	VM=36V			50	μΑ
Diode forward voltage	VD	ID=-2.0A		1.1	1.4	V
Current setting reference voltage	VRF	VREF=1.5V, Current ratio 100%		300		mV
Output short-circuit protection I	olock					
Timer latch time	Tscp			256		μs

Package Dimensions

unit: mm (typ)

SIP19 29.2x14.4 CASE 127CF ISSUE O

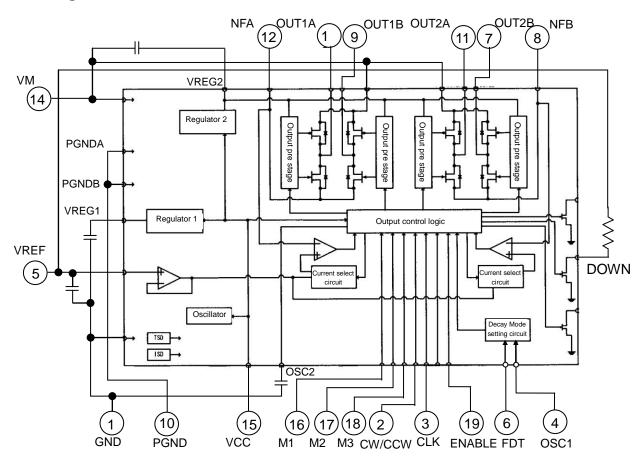




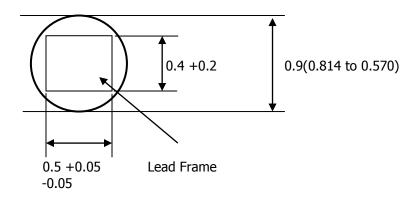
Pin Assignment

<u> </u>								
Pin No.	Pin symbol	Pin Functions						
1	GND	Circuit GND						
2	CW/CCW	Forward / Reverse signal input						
3	CLK	Clock pulse signal input						
4	OSC1	Chopping frequency setting capacitor connection						
5	VREF	Constant-current control reference voltage input						
6	FDT	Decay mode select voltage input						
7	OUT2B	B phase OUTB output						
8	NFB	B phase current sense resistance connection						
9	OUT1B	B phase OUTA output						
10	PGND	Power GND						
11	OUT2A	A phase OUTB output						
12	NFA	A phase current sense resistance connection						
13	OUT1A	A phase OUTA output						
14	VM	Motor supply connection						
15	VCC	Chip enable input						
16	M1							
17	M2	Excitation-mode switching pin						
18	M3							
19	ENABLE	Output enable signal input						

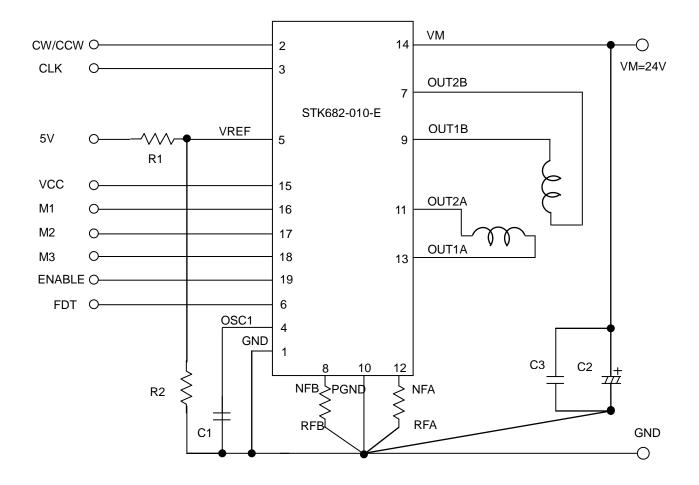
Block Diagram



Recommend hole size for Lead Frame on PCB; 0.9 mm(max)

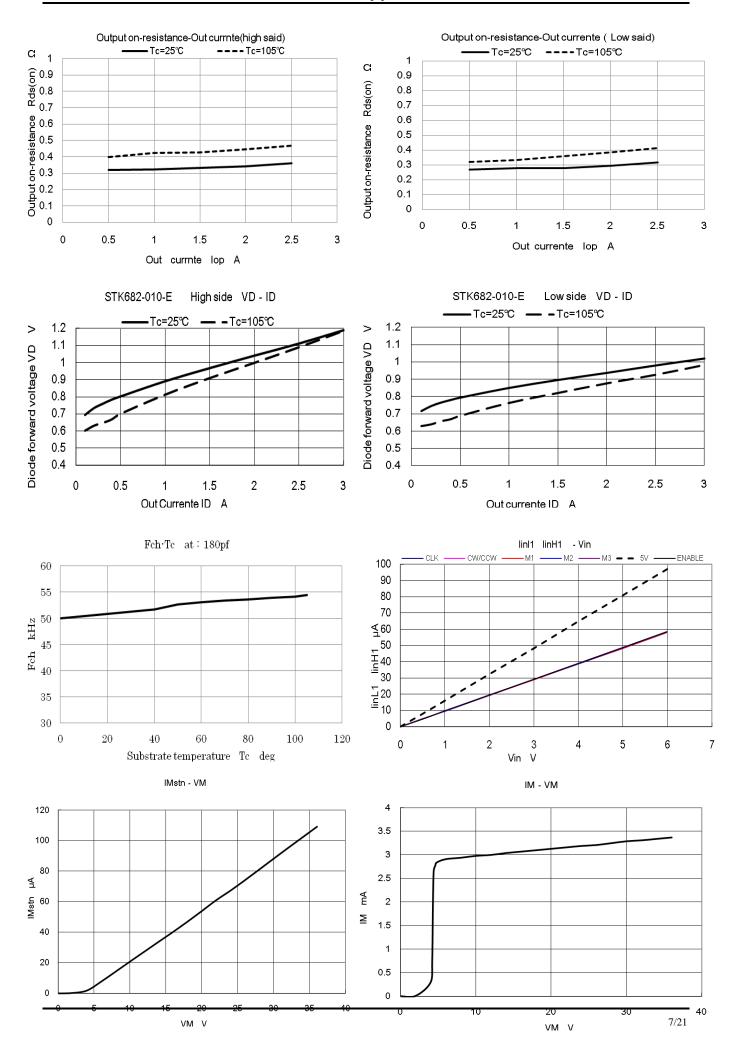


Application Circuit Example



Equivalent circuit diagram

Pin No.	Pin type	Equivalent Circuit Diagram
3 2 19 18 17 16	CLK CW/CCW ENABLE M3 M2 M1	VREQ1 O
15	VCC	Internal reset Input pin 1µF 300KΩ 100KΩ
13 10 14 12 11 9 8 7	OUT1A PGND VM NFA OUT2A OUT1B NFB OUT2B	
5	VREF	S DOWN S DOWN GND O T D S DOWN
4	OSC1	QNDO 4
6	FDT	$72k\Omega$ $23k\Omega$ $9k\Omega$ $16k\Omega$



Description of functions

(1) Excitation setting method

Set the excitation setting as shown in the following table by setting M1 pin, M2 pin and M3 pin

	Input signal			Initial	position
M3	M2	M1	MODE (Excitation)	A phase	
				current	B phase current
L	L	L	2 Phase	100%	-100%
L	L	Н	1-2 Phase	100%	0%
L	Н	L	W1-2 Phase	100%	0%
L	Н	Н	2W1-2 Phase	100%	0%
Н	L	L	4W1-2 Phase	100%	0%
Н	L	Н	8W1-2 Phase	100%	0%
Н	Н	Ĺ	16W1-2 Phase	100%	0%
Н	Н	Н	32W1-2 Phase	100%	0%

The initial position is also the default state at start-up and excitation position at counter-reset in each excitation mode

(2) Output current setting

Output current is set as shown below by the VREF pin (applied voltage) and a resistance value between NFA (B) pin and GND.

IOUT = (VREF / 5) / NFA (B) resistance

(Example) When VREF=1.5V and NFA (B) resistance is 0.3 Ω , the setting current is shown below. IOUT = (1.5 V / 5) / 0.3 Ω = 1.0 A

(3) Chip enable terminal/ VCC function

When Chip enable terminal/ V_{CC} pin is at low levels, the IC enters stand-by mode, all logic is reset and output is turned OFF.

When Chip enable terminal/ VCC pin is at high levels, the stand-by mode is released

(4) Step pin function

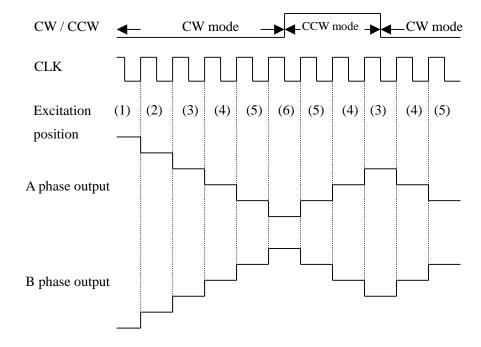
CLK pin step signal input allows advancing excitation step

Inp	out	Operation
VCC	CLK	
L	*	Stand-by mode
Н		Excitation step feed
Н	—	Excitation step hold

^{*} The setting value above is a 100% output current in each excitation mode.

(5) Forward / reverse switching function

CW/CCW	Operation
L	CW
Н	CCW

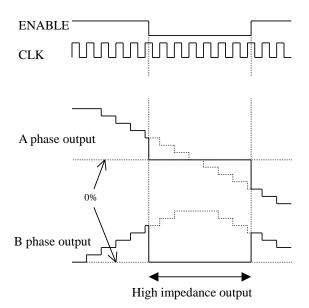


The internal D/A converter proceeds by a bit on the rising edge of the step signal input to the CLK pin. In addition, CW and CCW mode are switched by CW and CCW pin setting.

In CW mode, the B phase current is delayed by 90° relative to the A phase current. In CCW mode, the B phase current is advanced by 90° relative to the A phase current.

(6) Output enable function

When the ENABLE pin is set Low, the output is forced OFF and goes to high impedance. However, the internal logic circuits are operating, so the excitation position proceeds when the CLK is input. Therefore, when ENABLE pin is returned to High, the output level conforms to the excitation position proceeded by the CLK input.



(7) DECAY mode

The DECAY mode of the output current becomes only MIXED DECAY.

FDT voltage	DECAY method
3.5V to	SLOW DECAY
1.1V to 3.1V or OPEN	MIXED DECAY
to 0.8V	FAST DECAY

(8) Chopping frequency setting function

Chopping frequency is set as shown below by a capacitor between OSC1 pin and GND.

Fch =
$$1 / (C1 + 20pF / 10 \times 10^{-6})$$
 (Hz)

(Example) When Cosc1=100pF, the chopping frequency is shown below.

Fch =
$$1/((20+100)\times10^{-12}/10\times10^{-6})$$
 (Hz) = 83.3 (kHz)

Note

• The 20pF is a stray capacitance which is involved by the package of STK682-010-E.

(9) Output short-circuit protection circuit

Build-in output short-circuit protection circuit makes output to enter in stand-by mode. This function prevents the IC from damaging when the output shorts circuit by a voltage short or a ground short, etc. When output short state is detected, short-circuit detection circuit starts the operating and output is once turned OFF. After the timer latch time (typ: $256\mu s$), output is turned ON again. Still the output is at short state, the output is turned OFF and fixed in stand-by mode.

When output is fixed in stand-by mode by output short protection circuit, output is released the latch by setting Chip enable terminal/ V_{CC} ="L"

(10) Internal DOWN pin

The DOWN pin is an open drain connection.

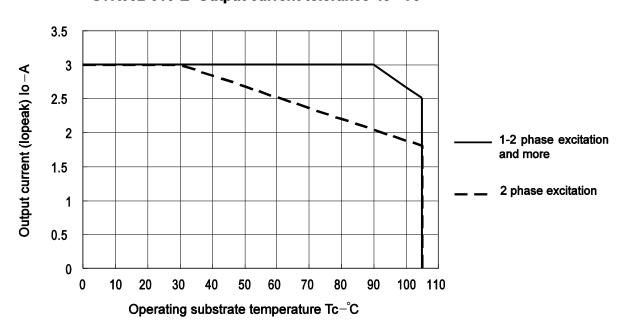
This pin is turned ON when no rising edge of CLK between the input signals while a period determined by a capacitor between OSC2 and GND, and outputs at low levels.

The DOWN pin output in once turned ON, is turned OFF at the next rising edge of CLK.

Holding current switching time (0.6sectyp) is set by an internal capacitor between OSC2 pin and GND.

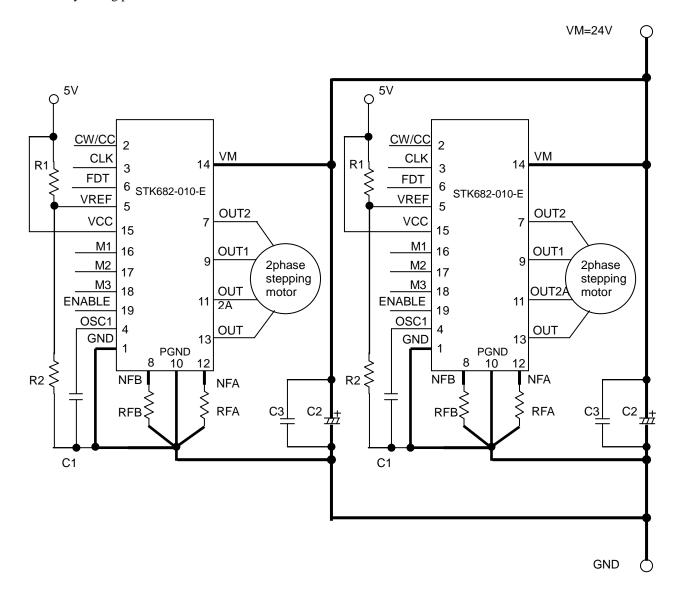
(11) Output current tolerance

STK682-010-E Output current tolerance lo-Tc

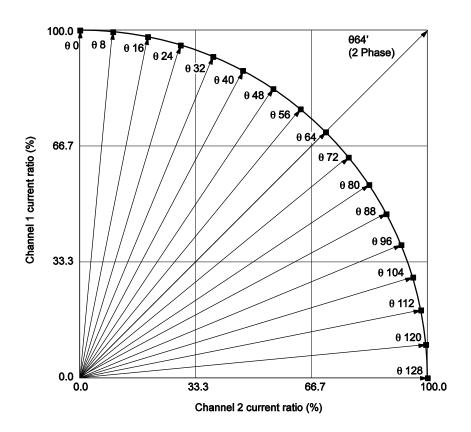


(12) When mounting multiple drivers on a single PC board

When mounting multiple drivers on a single PC board, the GND design should mount a VCC decoupling capacitor, C2 and C3, for each driver to stabilize the GND potential of the other drivers. The key wiring points are as follows.



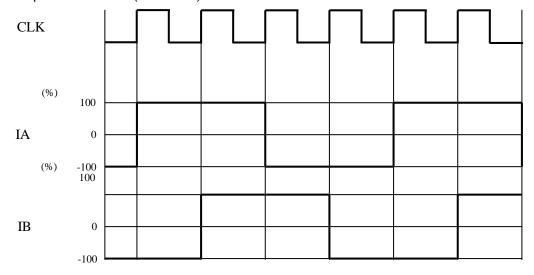
(13) Output current vector locus (1 step normalized 90°)

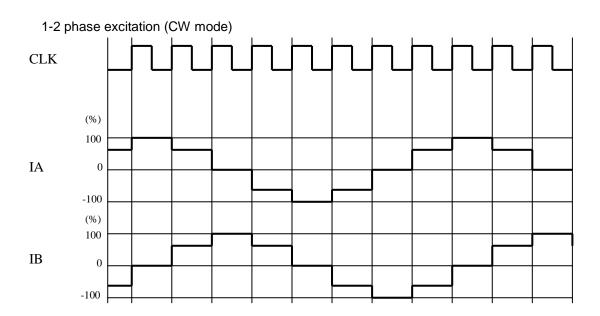


(14) Current setting ratio in each excitation mode

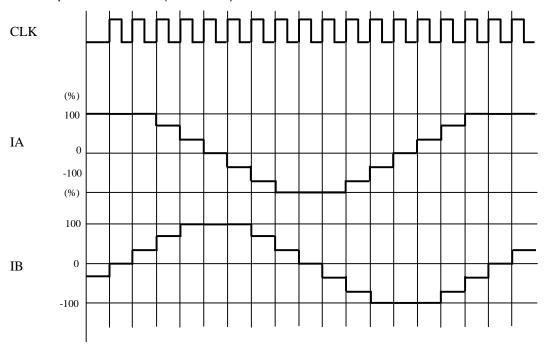
	2W1-2 n	hase/%	16W1-2	nhase(%)	8W1-2 n	hase(%)	4W1-2 p	hase(%)	2W1-2 n	hase/%)	W1-2 n	hase(%)	1-2 nh	ase(%)	2 nhas	se(%)		32W1.2	phase(%)	16W1-2	nhase(%	8W1.2 n	hase(%)	4W1-2	hasa(%)	2\\/1-2	nhase(%)	W1-2 n	120000	1-2 nh:	se(%)	2 nhs	ase(%)
STEP	Ach	Bch	Ach	Bch	Ach	Bch	Ach	Bch	Ach	Bch	Ach	Bch	Ach	Bch	Ach	Bch	STEP		Bch														
90	100	0		0				0				0		0			θ65	70															†
θ1	100	1															θ66	69	72	69	72												
θ2	100	2	100	2													θ67	68	73														
θ3	100	4															θ68	67			74	67	74										
θ4	100	5		5	100	5											θ69	66															
θ5	100	6															θ70	65		65	76												<u> </u>
θ6	100	7		7													θ71	64															
θ7	100	9															θ72	63			77	63	77	63	77								
θ8	100	10		10	100	10	100	10									θ73	62			L												
010	99	11		40													θ74 075	62			79												
θ10	99	12 13		12													θ75 θ76	61			- 00		80										
θ11 θ12	99 99	15		15	99	15											θ76 0 77	60 59		60	80	60	80										
θ13	99	16		13	99	13	-										θ78	58		58	82												
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θ17	98	21					1										θ82	53	84		84												1
θ18	98	22		22													θ83	52															
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θ20	97	24		24	97	24											θ85	50															
θ21	97	25															θ86	49			87												
θ22	96	27		27													θ87	48				<u>اي ل</u>		L.			<u> </u>						↓
θ23	96	28		- 00													889	47			88	47	88	47	88								Ļ—
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θ26 θ27	95	33		31			-										θ91 θ92	43			90	43	90										
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θ29	94	35	34	54	34	34											θ94	41		41	91												
θ30	93	36		36													095	39			-												†
θ31	93	37															096	38		38	92	38	92	38	92	38	92	38	92				
θ32	92	38		38	92	38	92	38	92	38	92	38					θ97	37															
θ33	92	39															998	36	93	36	93												
θ34	91	41		41													θ99	35															
θ35	91	42															θ100	34			94	34	94										
θ36	90	43		43	90	43											0101	33															Ь
θ37	90	44															θ102	31			95												<u> </u>
θ38 030	89	45		45													0103	30			00	20	00	- 00	00								₩
039	89	46		47	00	47		47									θ104	29			96	29	96	29	96								₩
θ40 θ41	88 88	47 48		47	88	47	88	47									θ105 θ106	28 27			96												\vdash
θ42	87	49		49													θ107	25			30												
θ43	86	50															0107	24			97	24	97										
043	86	51		51	86	51					Н						θ109	23			- 57		5,	\vdash									\vdash
θ45	85	52															θ110	22		22	98												
θ46	84	53		53													θ111	21	98														
θ47	84	55															θ112	20			98	20	98	20	98	20	98						
θ48	83	56		56	83	56	83	56	83	56							θ113	18															
θ49	82	57															θ114	17		17	99	Ш					lacksquare						$ldsymbol{oxed}$
θ50	82	58		58													θ115	16		L.	L .	Ц.		L_									₩
θ51	81	59									Ь						θ116	15			99	15	99	<u> </u>			-						₩
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θ53 θ54	80 79	61		62		 	1				\vdash						θ118 θ119	12 11			99	\vdash		<u> </u>			-						₩
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θ55	77	63		63	77	63	77	63			\vdash						θ120 θ121	9			100	10	100	10	100		-				_		-
θ57	77	64		- 03		- 03	- ' '	- 03									θ122	7			100	\vdash											\vdash
θ58	76	65		65							\vdash						θ123	6				\vdash		\vdash									-
θ59	75	66		- 50													θ124	5		5	100	5	100										\vdash
060	74	67		67	74	67											θ125	4		Ť	1	┌┤	.00										\vdash
061	73	68															θ126	2		2	100												
θ62	72	69		69													θ127	1															
θ63	72	70															θ128	0	100	0	100	0	100	0	100	0	100	0	100	0	100		
064	71	71	71	71	71	71	71	71	71	71	71	71	71	71	100	100																	

(15) Current wave example in each excitation mode (2 phase, 1-2 phase, W1-2 phase, 4W1-2 phase) 2 phase excitation (CW mode)

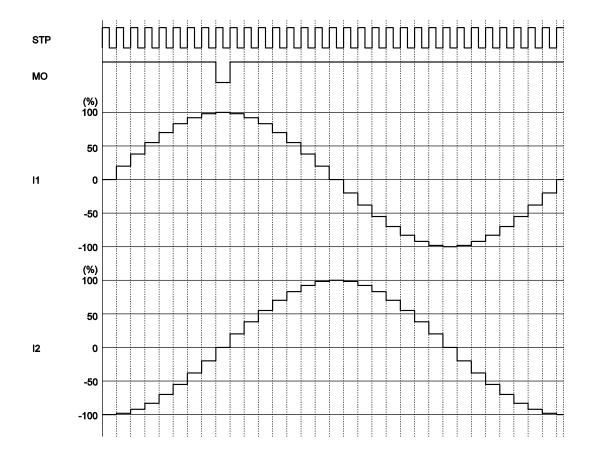




W1-2 phase excitation (CW mode)



4W1-2 phase excitation (CW mode)

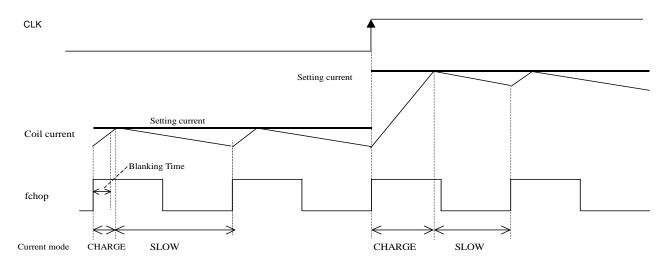


(16) Current control operation

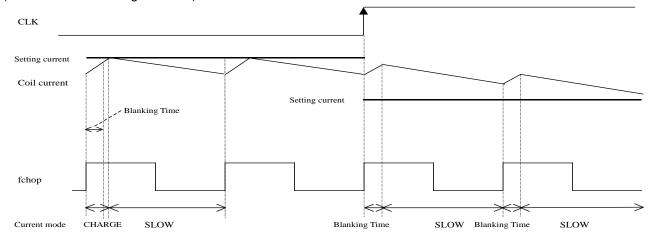
SLOW DECAY current control operation

When FDT pin voltage is a voltage over 3.5 V, the constant-current control is operated in SLOW DECAY mode.

(Sine-wave increasing direction)



(Sine-wave decreasing direction)



Each of current modes operates with the follow sequence.

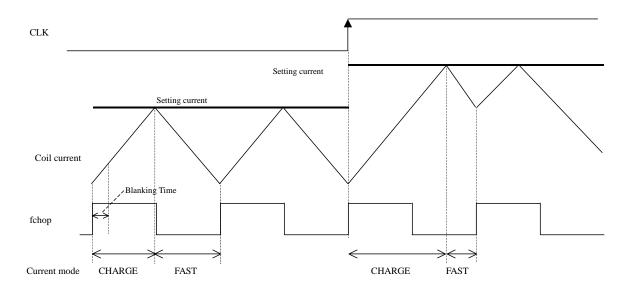
- The IC enters CHARGE mode at a rising edge of the chopping oscillation. (A period of CHARGE mode (Blanking Time) is forcibly present in approximately 1 µs, regardless of the current value of the coil current (ICOIL) and set current (IREF)).
- After the period of the blanking time, the IC operates in CHARGE mode until ICOIL ≥ IREF. After that, the mode switches to the SLOW DECAY mode and the coil current is attenuated until the end of a chopping period.

At the constant-current control in SLOW DECAY mode, following to the setting current from the coil current may take time (or not follow) for the current delay attenuation.

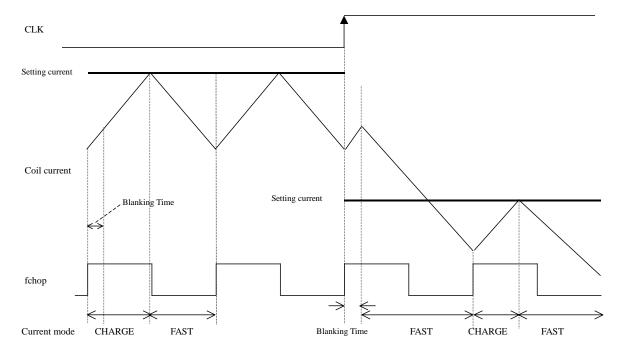
FAST DECAY current control operation

When FDT pin voltage is a voltage under 0.8V, the constant-current control is operated in FAST DECAY mode.

(Sine-wave increasing direction)



(Sine-wave decreasing direction)



Each of current modes operates with the follow sequence.

The IC enters CHARGE mode at a rising edge of the chopping oscillation.

(A period of CHARGE mode (Blanking Time) is forcibly present in approximately 1 µs, regardless of the current value of the coil current (ICOIL) and set current (IREF)).

After the period of the blanking time, The IC operates in CHARGE mode until ICOIL \geq IREF. After that, the mode switches to the FAST DECAY mode and the coil current is attenuated until the end of a chopping period. At the constant-current control in FAST DECAY mode, following to the setting current from the coil current takes short-time for the current fast attenuation, but, the current ripple value may be higher.

(Sine-wave increasing direction) CLK Setting current Coil current fchop

CHARGE

SLOW

FAST

CHARGE

SLOW

FAST

(Sine-wave decreasing direction) CLK Setting current Coil current Blanking Time Setting current

Each of current modes operates with the follow sequence.

SLOW

SLOW

FAST

CHARGE

Current mode

Current mode

The IC enters CHARGE mode at a rising edge of the chopping oscillation.

(A period of CHARGE mode (Blanking Time) is forcibly present in approximately 1 μ s, regardless of the current value of the coil current (ICOIL) and set current (IREF)).

Blanking Time

In a period of Blanking Time, the coil current (ICOIL) and the setting current (IREF) are compared.

If an ICOIL = IREF state exists during the charge period:

The IC operates in CHAGE mode until ICOIL \geq IREF. After that, it switches to SLOW DECAY mode and then switches to FAST DECAY mode in the last approximately 1 μ s of the period.

If no ICOIL = IREF state exists during the charge period:

The IC switches to FAST DECAY mode and the coil current is attenuated with the FAST DECAY operation until the end of a chopping period.

The above operation is repeated.

CHARGE

Normally, in the sine wave increasing direction the IC operates in SLOW (+FAST) DECAY mode, and in the sine wave decreasing direction the IC operates in FAST DECAY mode until the current is attenuated and reaches the set value and the IC operates in SLOW (+FAST) DECAY mode.

Power Dissipation

Power dissipation calculation of STK682-010-E following becomes.

2-phase excitation

 $Pd=IOH\times(Ronu+Rond)^2$

1-2-phase excitation

 $Pd=0.71\times IOH\times (Ronu + Rond)^2$

Please by substituting from electrical characteristic table value of Rond and Ronu.

Thermal design

[Operating range in which a heat sink is not used]

Use of a heat sink to lower the operating substrate temperature of the HIC (Hybrid IC) is effective in increasing the quality of the HIC.

The size of heat sink for the HIC varies depending on the magnitude of the average power loss, PdAV, within the HIC. The value of PdAV increases as the output current increases. To calculate PdAV, refer to "Calculating Internal HIC Loss for the STK672-640C-E in the specification document.

Calculate the internal HIC loss, PdAV, assuming repeat operation such as shown in Figure 1 below, since conduction during motor rotation and off time both exist during actual motor operations,



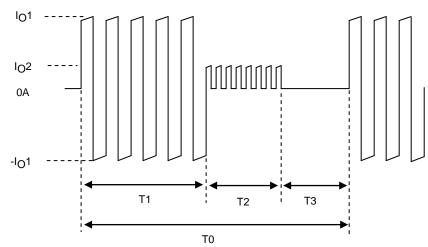


Figure 1 Motor Current Timing

T1 : Motor rotation operation time

T2: Motor hold operation time

T3: Motor current off time

T2 may be reduced, depending on the application.

T0: Single repeated motor operating cycle

IO1 and IO2: Motor current peak values

Due to the structure of motor windings, the phase current is a positive and negative current with a pulse form.

Note that figure 1 presents the concepts here, and that the on/off duty of the actual signals will differ.

The hybrid IC internal average power dissipation PdAV can be calculated from the following formula.

 $PdAV = (T1 \times P1 + T2 \times P2 + T3 \times 0) \cdot TO -----(I)$

(Here, P1 is the PdAV for IO1 and P2 is the PdAV for IO2)

If the value calculated using Equation (I) is 1.5W or less, and the ambient temperature, Ta, is 60°C or less, there is no need to attach a heat sink. Refer to Figure 2 for operating substrate temperature data when no heat sink is used.

[Operating range in which a heat sink is used]

Although a heat sink is attached to lower Tc if PdAV increases, the resulting size can be found using the value of c-a in Equation (II) below and the graph depicted in Figure 3.

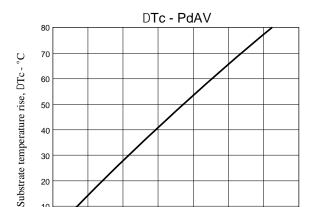
 $c-a = (Tc max-Ta) \cdot PdAV ---- (II)$

Tc max: Maximum operating substrate temperature =105°C

Ta: HIC ambient temperature

Although a heat sink can be designed based on equations (I) and (II) above, be sure to mount the HIC in a set and confirm that the substrate temperature, Tc, is 105°C or less.

Figure 2 Substrate temperature rise, ΔTc (no heat sink) - Internal average power dissipation, PdAV



1.5

Hybrid IC internal average power dissipation, PWIAV

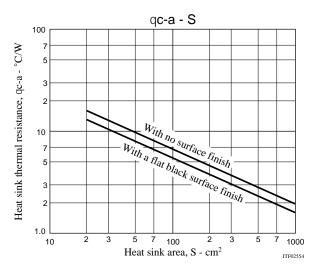
2.0

2.5

1.0

10

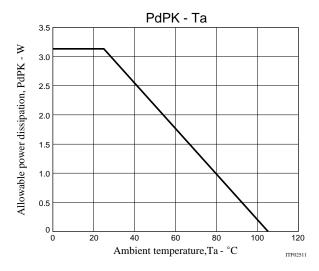
Figure 3 Heat sink area (Board thickness: 2mm) - θ c-a



Mitigated Curve of Package Power Loss, PdPK, vs. Ambient Temperature, Ta Package power loss, PdPK, refers to the average internal power loss, PdAV, allowable without a heat sink. The figure below represents the allowable power loss, PdPK, vs. fluctuations in the ambient temperature, Ta. Power loss of up to 3.1W is allowable at Ta=25°C, and of up to 1.75W at Ta=60°C.

3.0

Allowable power dissipation, PdPK(no heat sink) - Ambient temperature, Ta



ORDERING INFORMATION

Device	Package	Shipping (Qty / Packing)
STK682-010-E	SIP-19 (Pb-Free)	15 / Tube

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